

Product Change Notification - KSRA-29KJUY118

Date:

01 Aug 2018

Product Category:

8-bit Microcontrollers; Capacitive Touch Sensors

Affected CPNs:



Notification subject:

CCB 3211 Cancellation Notice: For the qualification of MTAI as an additional assembly site for selected Atmel products available in 32L VQFN package using palladium coated copper wire with gold flash (CuPdAu) bond wire.

Notification text:

PCN Status:

Cancellation notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

This change would have affected selected Atmel products available in 32L VQFN package assembled at ANAC Assembly site with punched as a singulation method, using palladium coated copper wire (PdCu) bond wire and 8290 die attach material.

Description of Change:

This qualification was originally performed to qualify MTAI as an additional assembly site for selected Atmel products available in 32L VQFN package using palladium coated copper wire with gold flash (CuPdAu) bond wire with sawn as a singulation method.

Impacts to Data Sheet:

Not applicable

Change Impact:

Not applicable

Reason for Change:

Microchip has decided not to qualify MTAI as an additional assembly site for selected Atmel products available in 32L VQFN package using palladium coated copper wire with gold flash (CuPdAu) bond wire.

Change Implementation Status:

Not applicable

Estimated Qualification Completion Date

Not applicable

Method to Identify Change:

Not Applicable

Revision History:

March 7, 2018: Issued initial notification.

March 22, 2018: Re-issued initial notification to revise the pre-change wire material to PdCu.

April 11, 2018: Re-issued to include singulation method and revise post change data.

August 1, 2018: Issued cancellation notice for the proposed qualification of MTAI as an additional assembly site for selected Atmel products available in 32L VQFN package using palladium coated copper wire with gold flash (CuPdAu) bond wire.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.



Attachment(s):

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

AT42QT4160-MUR

ATMEGA168-20MQ

ATMEGA168-20MQR

ATMEGA168-20MU

ATMEGA168-20MUR

ATMEGA168P-20MQ

ATMEGA168P-20MQR

ATMEGA168P-20MU

ATMEGA168P-20MUR

ATMEGA168PV-10MU

ATMEGA168PV-10MUR

ATMEGA168PV-10MUR455

ATMEGA168V-10MQ

ATMEGA168V-10MQR

ATMEGA168V-10MQR610

ATMEGA168V-10MU

ATMEGA168V-10MUR

ATMEGA168V-10MUR598

ATMEGA328-MU

ATMEGA328-MUR

ATMEGA328P-MN

ATMEGA328P-MNR

ATMEGA328P-MU

ATMEGA328P-MUR

ATMEGA48-20MU

ATMEGA48-20MUR

ATMEGA48V-10MU

ATMEGA48V-10MUR

ATMEGA48V-10MUR173

ATMEGA48V-10MUR348

ATMEGA48V-10MURA3

QT60160-ISG

QT60240-ISG

Date: Tuesday, July 31, 2018